

Package on Package (PoP) STACK Package Assembly - Photo CD-ROM

Photo CD-ROMs provide process, quality engineers, marketing or editorial staff with a unique source of photographs which may be used in company inspection documents, technical presentations and web sites. The photographs can also be used in marketing and advertising material or in technical articles. They may be simply pasted into any Word or PowerPoint document for in house company use. Photographs on the CD may be provided in .jpg or .Tiff file format.

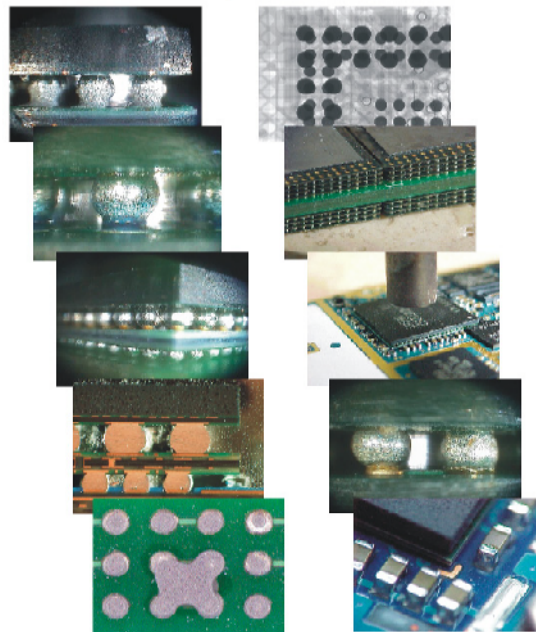
The PoP Photo CD-ROM contains over 380 images. The CD collection of photographs are either conventional photographs, x-ray images or microsections covering printed boards, surface mount or conventional joints as well as solder paste, components and solder joints. A selection of satisfactory and rejects images are provided on many of our photo CDs.

The CD photo album contains images that may be used freely provided the resulting product is not resold. The images may be used without reference but not credited or copyrighted to any other company or source. The images should not be incorporated into any other database or CD-ROM without permission. The seventeen photo CD ROMs are available for sale from Bob Willis. If you need some specific images for training course or presentation we can often provide other images or produce images for you.

Photo CD ROM is £99 plus VAT

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Bob Willis Package on Package (PoP) Assembly Photo Album



Package on Package applications are growing in popularity for mobile and handheld professional electronics. This photo CD provides over 360 images to help you produce training and inspection documents

Package on Package (PoP) Inspection & Process Defects - Wall Charts

A set of 25 colour wall charts available covering inspection and quality control in Package on Package (PoP) assembly. The photographic poster guide is ideal reference source in your organisation and is provided as an Acrobat pdf file. The individual sheets can be printed at A4 for bench top reference or as A3 colour posters for display for operator reference or as a training aid. The colour guide covers many of the following topics:

- Optical inspection of joints
 - X-ray inspection
 - Component alignment
 - Solder paste dipping
 - Liquid flux application
 - Paste & Flux depth monitoring
 - Open solder connections
 - Solder balling
 - Package warpage
 - Excess paste
 - Excess flux
 - BGA voiding
 - Package cracking
- Mask damage

Set of wall charts are £45 plus VAT

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Package on Package (PoP) STACK Package Assembly, Inspection & Rework - Interactive CD-ROM

Package on Package (PoP) applications are growing in popularity for mobile and handheld professional electronics applications and with it placing further demands on assembly engineers. In simple terms POP represents the stacking of components one on top of another either during the original component manufacture or during printed board assembly. As real estate is at a premium for logic and memory, PCB designers say the only way to go is up and up. POP packaging systems may include direct soldering, wire bonding or conductive adhesives for device-to-device interconnection. PoP is new to many contract and OEM assembly staff but with the demands of paste dipping, reflow warpage, increased placement accuracy/Z height control process introduction can be demanding. The difficulty in multi level ball inspection can be a challenge for x-ray equipment procedures as level one balls can mask level two and three interconnections. Manual inspection can be used but with these applications space is often not available for side viewing.

The CD covers an overview of the lead-free assembly process associated with PoP technology, and gives the opportunity to hear twelve engineers discuss the future and some of the practical issues associated with the assembly process.

Topics covered include:

- What is Package on Package (PoP)?
- Benefits of PoP Stack Packages
- Component Standards
 - Component Types
 - JEDEC Standards
- PCB Design Rules
 - Pad Layout
 - Via Hole Connection
- Lead-Free Assembly
- Engineering Interviews
- Stencil Printing
- POP Placement
 - Tack Flux
 - Dip Solder Paste
- Reflow Soldering PoP Packages
 - Convection
 - Vapour Phase
 - Temperature Profiling
- Inspection
 - Optical Inspection
 - X-ray inspection
- Underfill
- Rework
- Package on Package Defects



Interactive CD-ROM is £99 plus VAT

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